

Package Type Weight of Package (grams)	SC70-6 Lead 5.74E-03		Note: All weight has been calculated based on specified target or average values for a given material or process. Actual device weight may vary slightly.				
Component	Material	Weight in grams	Substance in material	Wt% in component	Weight of substance in milligrams	Wt% in finished product	Parts per Million
Lead Frame	Metal alloy	2.06E-03	Fe	55.41	1.14	35.92	359192
			Ni	42.00	0.87	19.90	199028
			Mn	0.80	0.02	15.09	150860
			Co	0.50	0.01	0.29	2874
			Si	0.30	0.01	0.18	1796
			Ag (DP plate)	0.99	0.01	0.11	1078
						0.36	0.02
Encapsulation	Epoxy	3.24E-03	Silica	73.10	2.37	56.49	564942
			Resin	25.00	0.81	41.30	412973
			Sb ₂ O ₃	0.10	0.00	14.12	141236
			Br	1.80	0.06	0.06	565
					1.02	10169	
Plating	Solder	2.74E-04	Sn	85.00	0.23	4.78	47811
			Pb	15.00	0.04	4.06	40639
					0.72	7172	
Chip	Silicon	1.48E-04	Si	99.00	0.15	2.58	25806
						2.55	25548
Die Attach	Eutectic						
Wire Bond	Gold Wire	1.29E-05	Au	99.99	0.01	0.22	2249
						0.22	2249



Environmental Statement Disclaimer

The information provided in this environmental statement is, to our knowledge, correct as of the date indicated on this page. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.